

ABSTRACT

An object of the invention is to provide an etching solution composition which adds an excellent etched surface morphology to a metal to be etched at a suppressed etch rate. The invention relates to an etching solution composition in which the etching solution composition contains (A) nitric acid, (B) acetic acid, (C) nitrilotris(methylene phosphonic acid), (D) a halogen compound and (E) water.

Figure 2